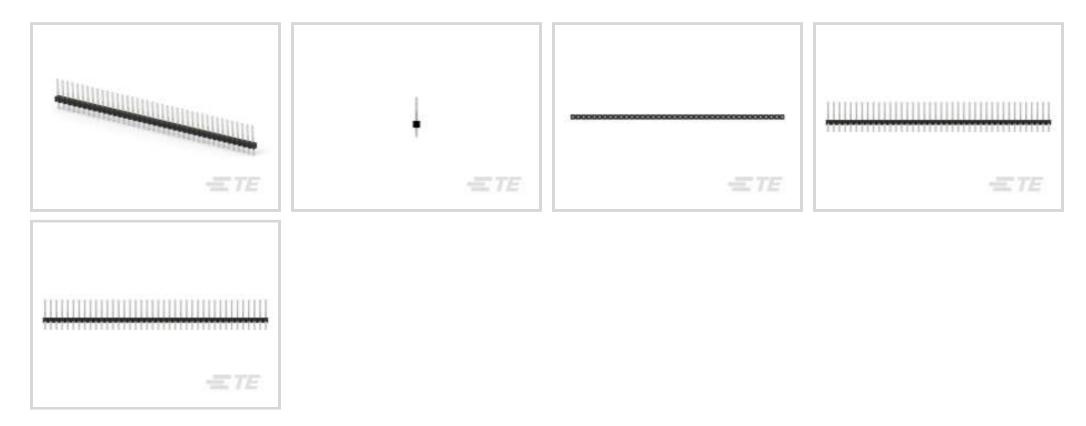
9-146274-0 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 9-146274-0 PCB Mount Header, Vertical, Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers

View on TE.com >

Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 40

Number of Rows: 1

Features



Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Breakaway
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Connector Contact Load Condition	Fully Loaded
PCB Mount Orientation	Vertical
Number of Positions	40
Number of Rows	1
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Operating Voltage	30 VAC
Body Features	

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PCB Mount Header, Vertical, Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers



Connector Profile	Standard
Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.64 mm[.025 in]
	100 – 200 µin
Contact Shape & Form	Square
Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Tin
Contact Mating Area Plating Material Thickness	2.54 – 5.08 μm[100 – 200 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	3.18 mm[.125 in]
Termination Method to Printed Circuit Board	Through Hole - Solder

Mechanical Attachment

Mating Alignment	Without
PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	LCP (Liquid Crystal Polymer), LCP-GF (Liquid Crystal Polymer)
Dimensions	
PCB Thickness (Recommended)	1.57 mm[.062 in]
Usage Conditions	
Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]
Operation/Application	

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Solder Process Feature	Board Standoff
Circuit Application	Signal
Industry Standards	
Approved Standards	CSA LR7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	100
Packaging Type	Carton
Product Compliance	
For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023
	(235) Candidate List Declared Against: IUNE
	Candidate List Declared Against: JUNE 2023 (235)
	Does not contain REACH SVHC

Halogen Content

Low Bromine/Chlorine - Br and Cl < 900 ppm per homogenous material. Also BFR /CFR/PVC Free

Pin-in-Paste capable to 260°C

Solder Process Capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

PCB Mount Header, Vertical, Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers





Also in the Series AMPMODU Headers

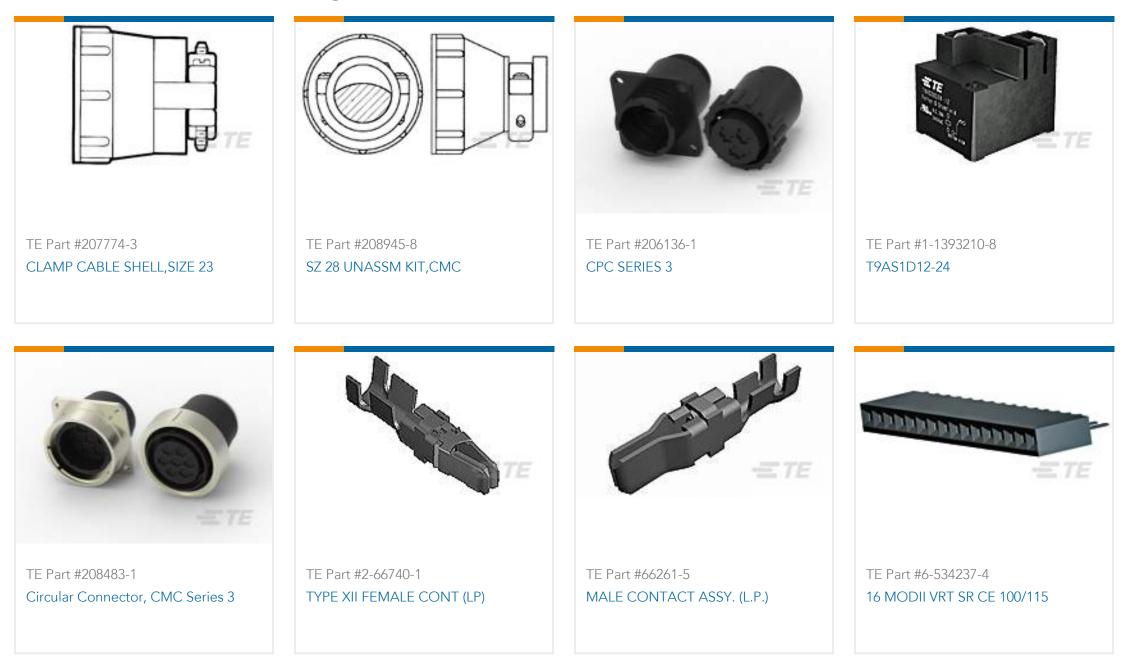




Wire-to-Board Connector AssembliesWire-to-& Housings(5)Image: Connector Assemblies

Wire-to-Board Connector Contacts(65)

Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 40 Position, 2.54 mm [.1 in] Centerline, Breakaway, Tin, Through Hole - Solder, Signal, AMPMODU Headers



Documents

CAD Files 3D PDF

3D

Customer View Model

ENG_CVM_CVM_9-146274-0_E.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_9-146274-0_E.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_9-146274-0_E.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5

English

Product Environmental Compliance TE Material Declaration

English